

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

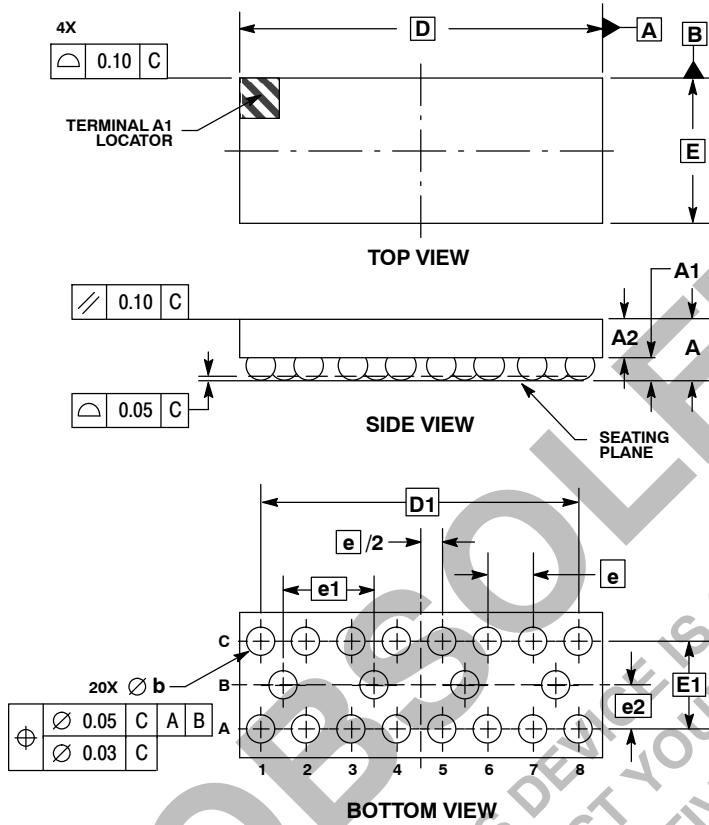
ON Semiconductor®



A1
SCALE 4:1

FLIP-CHIP-20
CASE 499AS
ISSUE B

DATE 17 DEC 2019

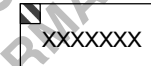


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.650
A1	0.210	0.270
A2	0.280	0.380
b	0.290	0.340
D	4.000 BSC	
D1	3.500 BSC	
E	1.600 BSC	
E1	0.870 BSC	
e	0.500 BSC	
e1	1.000 BSC	
e2	0.435 BSC	

GENERIC MARKING DIAGRAM*



XXXXXXXX = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking.

DOCUMENT NUMBER:	98AON21910D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	20 PIN FLIP-CHIP, 4.0x1.6 MM, 0.5 PITCH	PAGE 1 OF 2

